

N-Channel 100-V (D-S) MOSFET

PRODUCT	SUMMARY	Y				
V _{(BR)DSS} (V)	r _{DS(on)} (Ω)	I _D (A)				
100	0.034 at V _{GS} = 10 V	50 ^a				

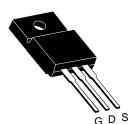
FEATURES

- TrenchFET[®] Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R_g Tested

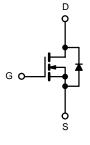
APPLICATIONS

• Isolated DC/DC Converters





TO-220 FULLPAK



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _C = 25 °C, unless oth	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	100	V	
Gate-Source Voltage		V _{GS}	± 20	v
Continuous Drain Current ($T_1 = 175 ^{\circ}C$)	T _C = 25 °C	50 ^a		
Continuous Drain Current $(1_j = 175 \text{ C})$	T _C = 125 °C	I _D	28 ^a	A
Pulsed Drain Current		I _{DM}	120	A
Avalanche Current	L = 0.1 mH	I _{AS}	31	
Single Pulse Avalanche Energy ^b			61	mJ
	T _C = 25 °C	P	360 ^c	
Maximum Power Dissipation ^b	T _A = 25 °C ^d	– P _D –	3.70	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-263) ^d	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)		R _{thJC}	0.4	C/W	

Notes:

a. Package limited.

b. Duty cycle \leq 1 %.

c. See SOA curve for voltage derating.

d. When Mounted on 1" square PCB (FR-4 material).

BMB1104N					B	^R VBse
					www.V	/Bsemi
SPECIFICATIONS $T_J = 25$ °	C, unless o	therwise noted				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{DS} = 0 V, I_D = 250 \mu A$	100			V
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.5		2.5	v
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1	μA
Zero Gate Voltage Drain Current		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C			50	
		$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 \text{ °C}$			250	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	120			Α
		V _{GS} = 10 V, I _D = 30 A		0.034		
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.063		Ω
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.084		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S
Dynamic ^b	ı		ı	•	ı	
Input Capacitance	C _{iss}			5100		
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		480		pF
	C	4 -		210	1	1

D y manne						
Input Capacitance	C _{iss}			5100		
Output Capacitance	C _{oss}	$V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz$		480		pF
Reverse Transfer Capacitance	C _{rss}			210		
Total Gate Charge ^c	Qg			90	130	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 65 \text{ A}$		23		nC
Gate-Drain Charge ^c	Q _{gd}			34		
Gate Resistance	R _g		0.5	1.7	3.3	Ω
Turn-On Delay Time ^c	t _{d(on)}			24	35	
Rise Time ^c	t _r	V_{DD} = 100 V, R _L = 1.5 Ω		220	330	
Turn-Off Delay Time ^c	t _{d(off)}	$\rm I_D \cong 65$ A, $\rm V_{GEN}$ = 10 V, $\rm R_g$ = 2.5 Ω		45	70	ns
Fall Time ^c	t _f			200	300	
Source-Drain Diode Ratings and Ch	aracteristics 7	$\Gamma_{\rm C} = 25 \ {}^{\circ}{\rm C}^{\rm b}$				•
Continuous Current	۱ _S			50		٨
Pulsed Current	I _{SM}			120		A
Forward Voltage ^a	V _{SD}	I _F = 65 A, V _{GS} = 0 V		1.0	1.5	V
Reverse Recovery Time	t _{rr}			130	200	ns
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, di/dt = 100 A/μs		8	12	А
Reverse Recovery Charge	Q _{rr}	1		0.52	1.2	μC

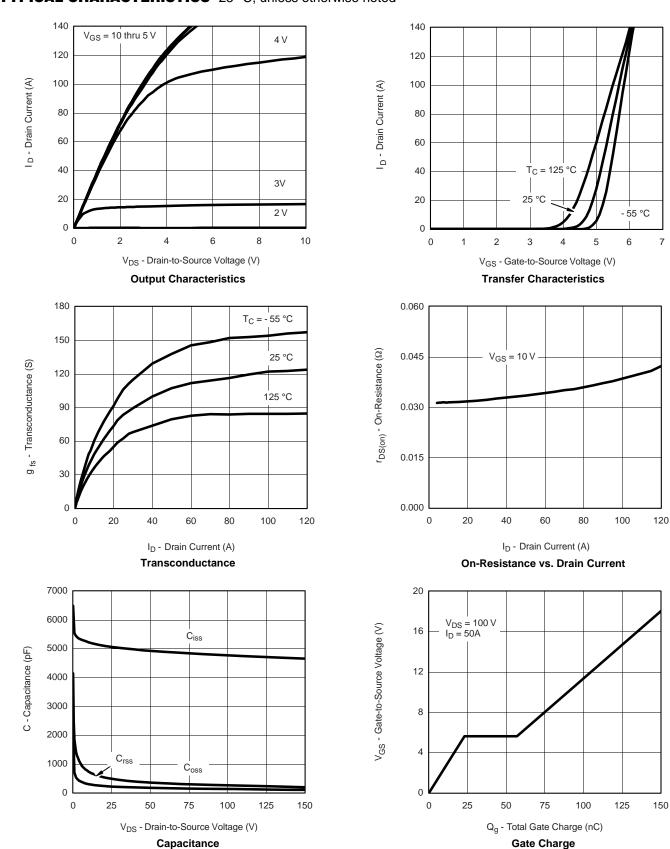
Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

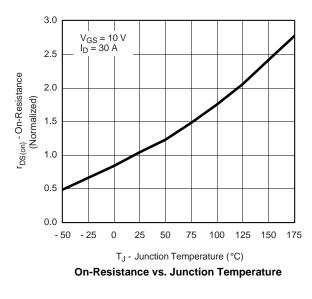


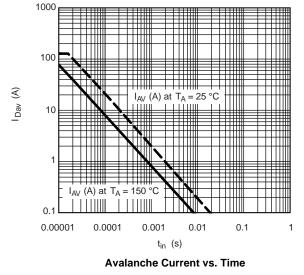


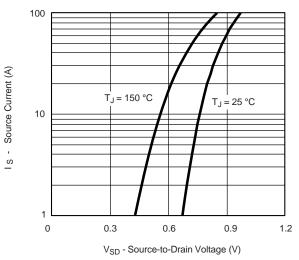
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



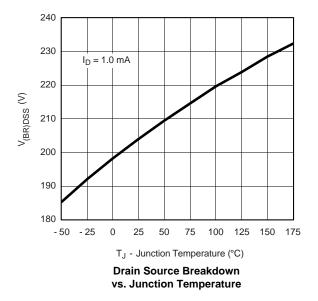
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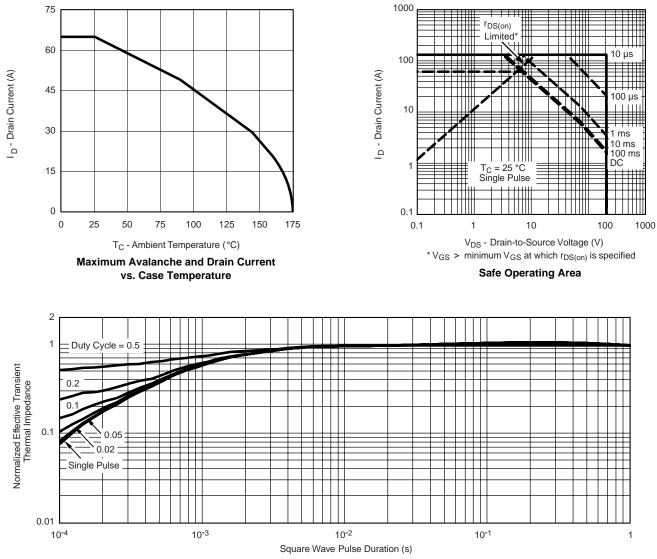
Source-Drain Diode Forward Voltage



VBMB1104N



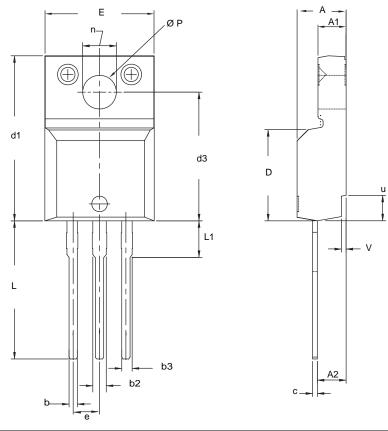
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



TO-220 FULLPAK (HIGH VOLTAGE)



	MILL	IMETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.5	4 BSC	0.100 BSC		
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØP	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	
u	2.400 0.400	2.500	0.094		

Notes

1. To be used only for process drawing. 2. These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads. 3. All critical dimensions should C meet $C_{pk} > 1.33$. 4. All dimensions include burrs and plating thickness. 5. No chipping or package damage.



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